SDAS124C - APRIL 1982 - REVISED AUGUST 1996

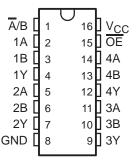
- 3-State Outputs Interface Directly With System Bus
- Provide Bus Interface From Multiple Sources in High-Performance Systems
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

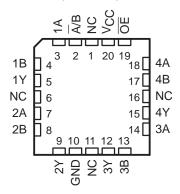
These data selectors/multiplexers are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable ( $\overline{OE}$ ) input is at a high logic level.

The SN54ALS257A and SN54ALS258A are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS257A, SN74ALS258A, SN74AS257, and SN74AS258 are characterized for operation from 0°C to 70°C.

SN54ALS257A, SN54ALS258A . . . J PACKAGE SN74ALS257A, SN74ALS258A, SN74AS257, SN74AS258 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS257A, SN54ALS258A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### **FUNCTION TABLE**

	INP	JTS		OUTPUT Y				
	j.	DATA		SN54ALS257A	SN54ALS258A			
OE	A/B	Α	В	SN74ALS257A SN74AS257	SN74ALS258A SN74AS258			
Н	Χ	Х	Χ	Z	Z			
L	L	L	Χ	L	Н			
L	L	Н	Χ	Н	L			
L	Н	Х	L	L	Н			
L	Н	Х	Н	Н	L			



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SDAS124C - APRIL 1982 - REVISED AUGUST 1996

#### logic symbols†

#### SN54ALS257A, SN74ALS257A, SN74AS257 15 OE ΕN 1 G1 A/B 1A MUX▷ 3 1Y 1B 5 2A 6 2B 11 **3A** 9 10 3B 14 4A 12 13 4B

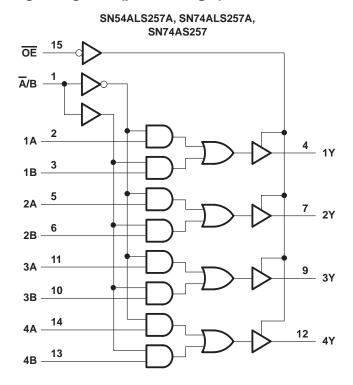
#### SN54ALS258A, SN74ALS258A, SN74AS258 15 ŌĒ ΕN 1 G1 A/B 1A MUX⊳ 3 1Y $\nabla$ 1B 5 2A 7 6 2B 11 **3A** 9 10 **3Y** 3B 14 4A 12

4Y

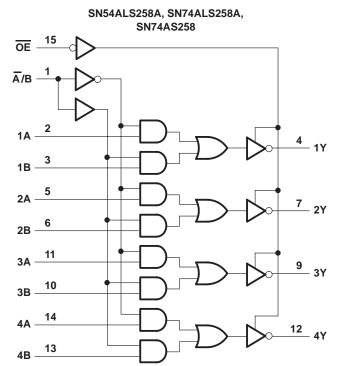
13

4B

#### logic diagrams (positive logic)



Pin numbers shown are for the D, J, and N packages.





<sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

SDAS124C - APRIL 1982 - REVISED AUGUST 1996

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>I</sub>	
Voltage applied to a disabled 3-state output	
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 1):	D package 1.3 W
•	N package1.1 W
Operating free-air temperature range, TA: SN54ALS257A, SN54A	LS258A –55°C to 125°C
SN74ALS257A, SN74A	LS258A 0°C to 70°C
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN54ALS257A SN54ALS258A			SN74ALS257A SN74ALS258A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

SDAS124C - APRIL 1982 - REVISED AUGUST 1996

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CON	TEST CONDITIONS			7A BA	SN74ALS257A SN74ALS258A			UNIT
			MIN	TYP†	MAX	MIN	TYP <sup>†</sup>	MAX		
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.5			-1.5	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			
Vон		V 45 V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
		V <sub>CC</sub> = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2		
V		V 45V	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	٧
VOH		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA					0.35	0.5	V
lozh		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			20			20	μΑ
lozL		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.4 V$			-20			-20	μΑ
ТĮ		$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1			0.1	mA
lіН		$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>IL</sub>		$V_{CC} = 5.5 \text{ V},$	$V_{ } = 0.4 V$			-0.1			-0.1	mA
I <sub>O</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		3	8		3	6	
	SN54ALS257A, SN74ALS257A	V <sub>CC</sub> = 5.5 V	Outputs low		8	12		8	12	
	GIVI 47 LEGZOTT		Outputs disabled		9	14		9	14	mA
Icc			Outputs high		2.5	5	·	2.5	4	
	SN54ALS258A, SN74ALS258A	1 1 1 2 2 2 2 2 2	Outputs low		7	11		7	11	
	SN/4ALS258A		Outputs disabled		8	13		8	13	

 $<sup>\</sup>overline{\dagger}$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> ( C <sub>L</sub> : R1 : R2 : T <sub>A</sub> :	UNIT			
			SN54AL	S257A	SN74ALS257A		
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A on D	Any Y	2	12	2	10	ns
<sup>t</sup> PHL	A or B		2	14	2	12	
<sup>t</sup> PLH		A V	4	21	6	18	
<sup>t</sup> PHL	Ā/B	Any Y	6	25	6	22	ns
<sup>t</sup> PZH	ŌĒ	A	3	20	4	16	
t <sub>PZL</sub>	OE	Any Y	4	22	5	18	ns
<sup>t</sup> PHZ	ŌĒ	Any V	2	12	2	10	no
tPLZ	OE .	Any Y	2	35	4	15	ns

<sup>§</sup> For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>&</sup>lt;sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

SDAS124C - APRIL 1982 - REVISED AUGUST 1996

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> : R1 : R2 :	= 50 pF, = 500 $\Omega$ , = 500 $\Omega$ , = MIN to		S258A	UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A on D	Any Y	1	12	2	8	ns
t <sub>PHL</sub>	A or B		2	9	2	7	
tPLH	Ā/B	Any Y	4	28	5	25	
t <sub>PHL</sub>	A/B		5	25	6	20	ns
<sup>t</sup> PZH	ŌĒ	A \/	3	20	4	18	
<sup>t</sup> PZL	ÜE	Any Y	5	21	5	18	ns
t <sub>PHZ</sub>	ŌĒ	Any V	2	12	2	10	20
t <sub>PLZ</sub>	OE .	Any Y	3	37	4	18	ns

<sup>†</sup> For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Voltage applied to a disabled 3-state output	
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 1): D package	1.3 W
N package	
Operating free-air temperature range, T <sub>A</sub> : SN74AS257, SN74AS258 0°C to	70°C
Storage temperature range, T <sub>stg</sub> 65°C to	150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN74AS257 SN74AS258			UNIT
		MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			8.0	V
loh	High-level output current			-15	mA
loL	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

SDAS124C - APRIL 1982 - REVISED AUGUST 1996

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TES	TEST CONDITIONS			7 3	UNIT
				MIN	TYP†	MAX	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2	V
.,		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V
VOH		V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -15 mA	2.4	3.2		V
VOL		V <sub>CC</sub> = 4.5 V,	$I_{OL} = 48 \text{ mA}$		0.35	0.5	V
lozh		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			50	μΑ
lozL		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.4 V			-50	μΑ
A,	A, B, or OE					0.1	
l <sub>l</sub>	Ā/B	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.2	mA
	A, B, or OE					20	
lн	Ā/B	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			40	μΑ
	A, B, or OE	V 55V	V 0.4V			-0.5	
I∣L	Ā/B	$V_{CC} = 5.5 \text{ V},$	$V_I = 0.4 V$	-		-1	mA
lo <sup>‡</sup>		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA
			Outputs high		12.1	19.7	
	SN74AS257	V <sub>CC</sub> = 5.5 V	Outputs low		19	30.6	mA
laa			Outputs disabled		19.7	31.9	
Icc	SN74AS258		Outputs high		8.4	13.5	
		4AS258 V <sub>CC</sub> = 5.5 V	Outputs low		15.2	24.6	
			Outputs disabled		15.5	25.2	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SDAS124C - APRIL 1982 - REVISED AUGUST 1996

#### switching characteristics (see Figure 1)

PARAMETER	PARAMETER FROM TO (OUTPUT)		$V_{CC}$ = 4.5 V f $C_L$ = 50 pF, R1 = 500 Ω, R2 = 500 Ω, $T_A$ = MIN to N	UNIT		
			MIN	MAX		
tPLH t	A or B	Any Y	1	5.5	ns	
t <sub>PHL</sub>	7010	Ally I	1	6	113	
tPLH	Ā/B	Any	2	11		
<sup>t</sup> PHL	A/B	Any Y	2	10	ns	
<sup>t</sup> PZH	<del></del>	Aman	2	7.5		
t <sub>PZL</sub>	ŌĒ	Any Y	2	9.5	ns	
<sup>†</sup> PHZ	ŌĒ	Any Y	1.5	6.5	ne	
t <sub>PLZ</sub>	)E	Ally I	2	7	ns	

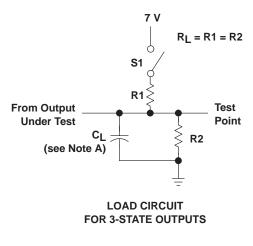
#### switching characteristics (see Figure 1)

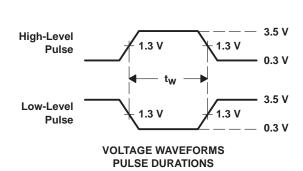
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$ = 4.5 V t $C_L$ = 50 pF, R1 = 500 $\Omega$ , R2 = 500 $\Omega$ , T <sub>A</sub> = MIN to I	UNIT		
			MIN	MAX		
tPLH	A or B	Any	1	5	ns	
<sup>t</sup> PHL	AOIB	Any Y	1	4		
<sup>t</sup> PLH	Ā/B	Amerik	2	9.5	ns	
<sup>t</sup> PHL	A/B	Any Y	2	10		
<sup>t</sup> PZH		A V	2	8		
<sup>t</sup> PZL	ŌĒ	Any Y	2	10	ns	
t <sub>PHZ</sub>	ŌĒ	Anux	1.5	6		
t <sub>PLZ</sub>	OE .	Any Y	2	6.5	ns	

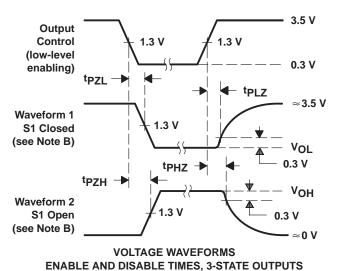
<sup>†</sup> For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

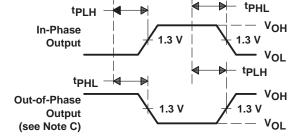
SDAS124C - APRIL 1982 - REVISED AUGUST 1996

# PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES









.3 V

Input

3.5 V

0.3 V

1.3 V

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





www.ti.com 11-Nov-2009

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-88626012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8862601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-8862601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
85097012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8509701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
8509701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54ALS257AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN74ALS257AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS257ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS257ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS257ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS258AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS258ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM



#### PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74AS257DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS257NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS257NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS257NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS258DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS258DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS258DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS258N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS258NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS258NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS258NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS258NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS257AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS257AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54ALS257AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54ALS258AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS258AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54ALS258AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



#### PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

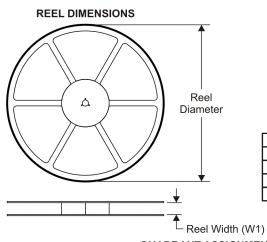
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 29-Jul-2009

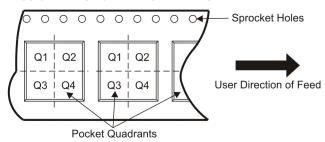
#### TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
P	<b>〈</b> 0	Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
П	P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS257ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS257ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ALS258ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AS257NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS258DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AS258NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 29-Jul-2009



\*All dimensions are nominal

All difficultions are florifical							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS257ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS257ANSR	SO	NS	16	2000	346.0	346.0	33.0
SN74ALS258ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AS257NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74AS258DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AS258NSR	SO	NS	16	2000	346.0	346.0	33.0

#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

#### **MECHANICAL DATA**

#### NS (R-PDSO-G\*\*)

### 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



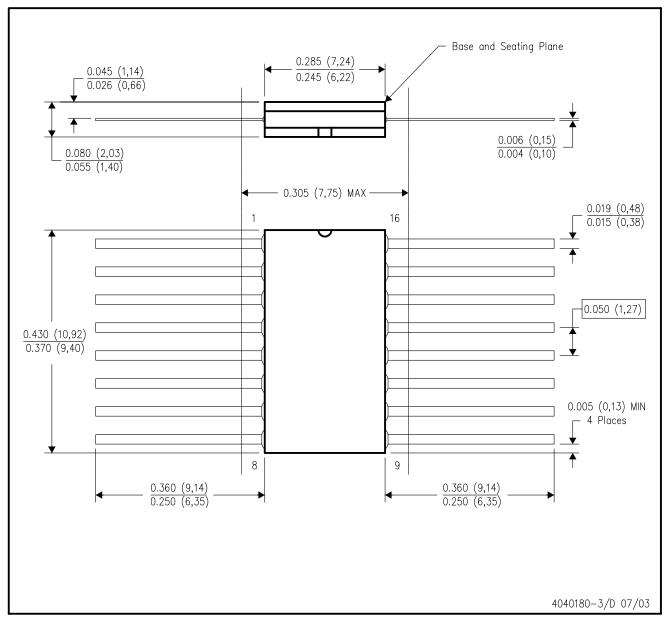
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## W (R-GDFP-F16)

#### CERAMIC DUAL FLATPACK

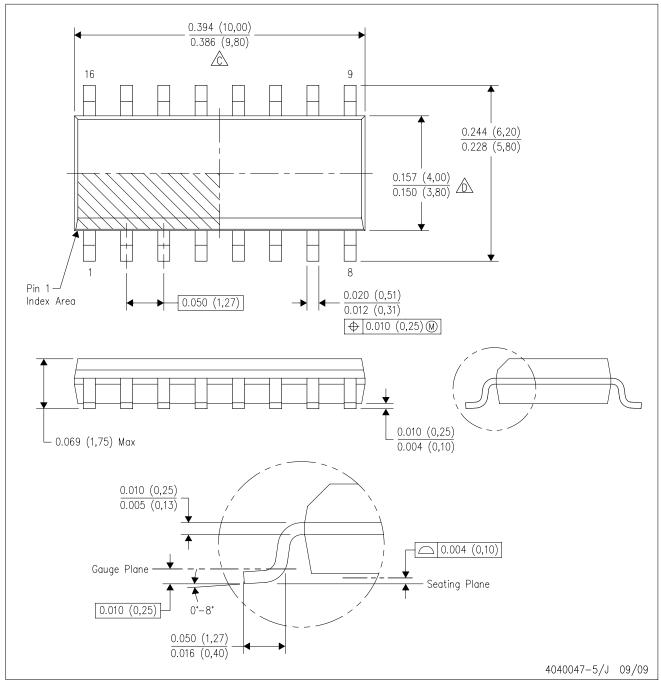


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



#### D (R-PDS0-G16)

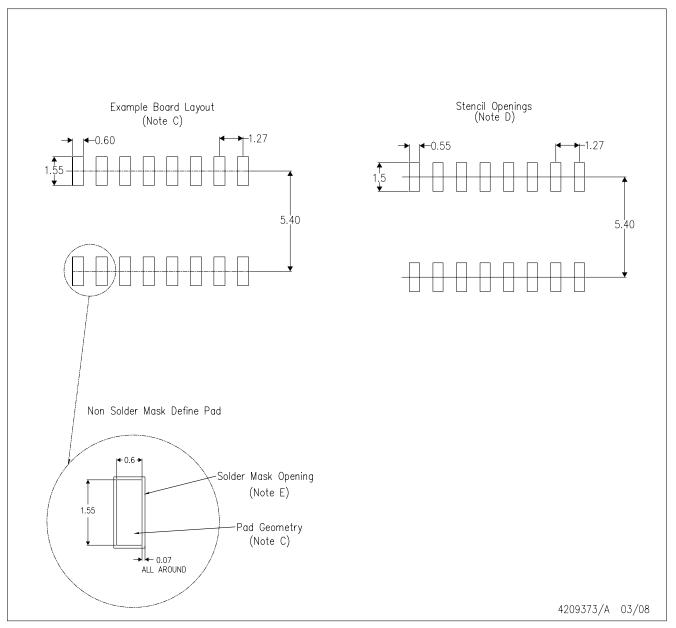
#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



## D(R-PDSO-G16)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### N (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

**Applications Products Amplifiers** amplifier.ti.com Audio www.ti.com/audio Data Converters Automotive www.ti.com/automotive dataconverter.ti.com DLP® Products Broadband www.dlp.com www.ti.com/broadband DSP Digital Control dsp.ti.com www.ti.com/digitalcontrol Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Military Interface www.ti.com/military interface.ti.com Optical Networking Logic logic.ti.com www.ti.com/opticalnetwork Power Mgmt power.ti.com Security www.ti.com/security Telephony Microcontrollers microcontroller.ti.com www.ti.com/telephony Video & Imaging www.ti-rfid.com www.ti.com/video RF/IF and ZigBee® Solutions www.ti.com/lprf Wireless www.ti.com/wireless

> Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated